



Application Data Sheet

Application Information

Application Number:: 10681583
Filing Date:: 10/08/2003
Application Type:: Regular
Subject Matter:: Utility
Title:: Semiconductor multi-package module having inverted second package stacked over die-down die-up flip-chip ball grid array (BGA) package
Attorney Docket Number:: CPAC 1029-5 D3
Total Drawing Sheets:: 20
Small Entity?:: No

Applicant Information

Applicant Authority Type: Inventor
Primary Citizenship Country: US
Status: Full Capacity
Given Name: Marcos
Family Name: Karnezos
City of Residence: Palo Alto
State or Province of Residence: CA
Country of Residence: US
Street of mailing address: 535 Lytton Avenue
City of mailing address: Palo Alto
State or Province of mailing address: CA
Country of mailing address: US
Postal or Zip Code of mailing address: 94301



Correspondence Information

Correspondence Customer Number:: 22470

Representative Information

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| Representative Customer Number:: | 22470 | |
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Domestic Priority Information

| Application:: | Continuity Type:: | Parent Application:: | Parent Filing Date:: |
|------------------|-------------------------|----------------------|----------------------|
| This Application | Non-Provisional of | 60/417,277 | October 8, 2002 |
| This Application | Non-Provisional of | 60/460,541 | April 4, 2003 |
| This Application | Continuation-in-Part of | 10/618,933 | July 14, 2003 |
| 10/618,933 | Non-Provisional of | 60/460,541 | April 4, 2003 |

Assignee Information

Assignee name:: ChipPAC, Inc.
Street of mailing address:: 47400 Kato Road
City of mailing address:: Fremont
State or Province of mailing address:: CA
Country of mailing address:: US
Postal or Zip Code of mailing address:: 94538